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A great diversity of interconnect & thermal solutions
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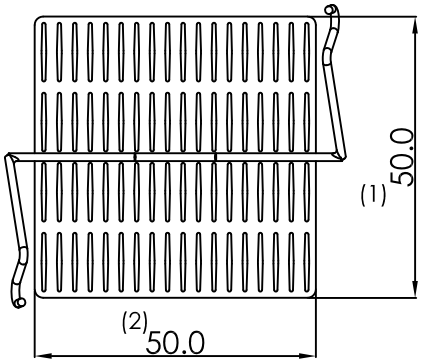
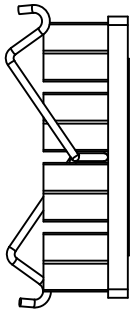
TEL: 886-2-2643-6558 FAX:886-2-2643-6118 www.regothermal.com

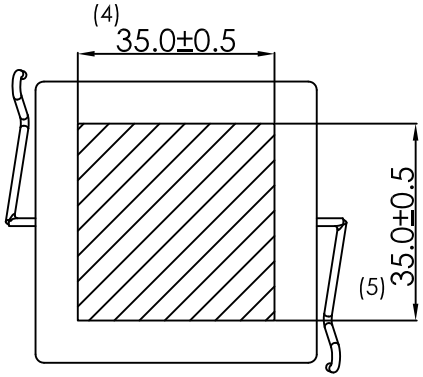
APPROVAL SHEET

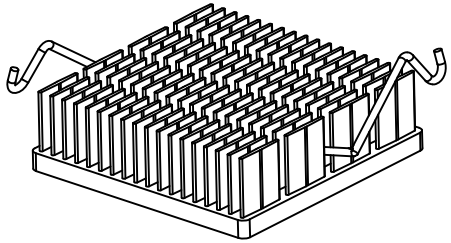
BRAND	REGO
PART NUMBER	FN50004-xx35BA+PCM
DESCRIPTION	HEAT SINK ASSEMBLY 50 x 50 x (6~40)mm
CUSTOMER	
CUSTOMER P/N	

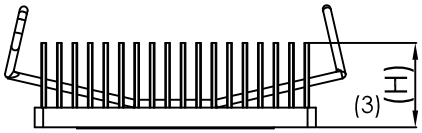
AUTHORIZED SIGNATURES			
NAME			
DATE			





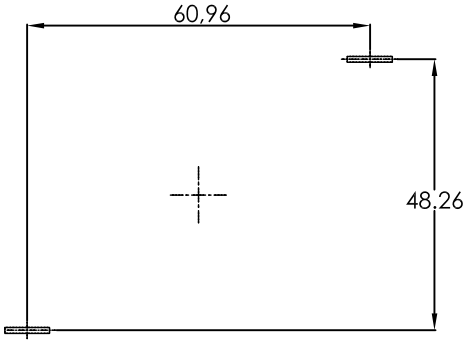






NOTES:

PART NAME / NUMBER	HEIGHT(H)	FORGED FIN	PCS	WIRE CLIP	PCS	ANCHOR	PCS	PHASE CHANGE THERMAL PAD	PCS
FN50004-0635BA+PCM	6	FN50004-0635BA-N							
FN50004-0835BA+PCM	8	FN50004-0835BA-N							
FN50004-1035BA+PCM	10	FN50004-1035BA-N							
FN50004-1535BA+PCM	15	FN50004-1535BA-N							
FN50004-2035BA+PCM	20	FN50004-2035BA-N	1	BCL6053-18	1	81921U-91-03TB01	2	PCM4988 35x35x0.2	1
FN50004-2535BA+PCM	25	FN50004-2535BA-N							
FN50004-3035BA+PCM	30	FN50004-3035BA-N							
FN50004-3535BA+PCM	35	FN50004-3535BA-N							
FN50004-4035BA+PCM	40	FN50004-4035BA-N							

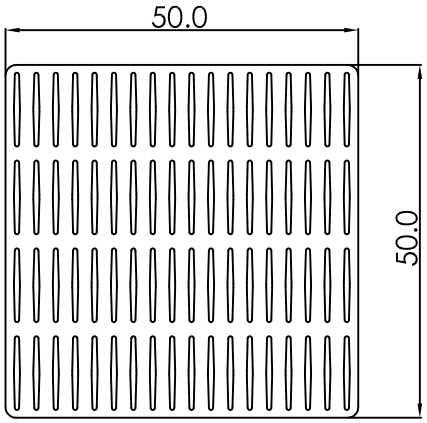


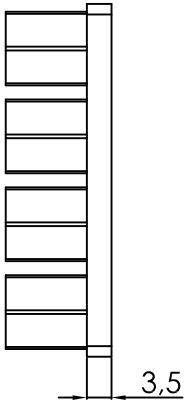
REF : ANCHOR LAYOUT

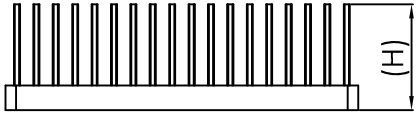
COMPRESSION REFERENCE

CONDITIONED	H+T = 2.9mm IC HEIGHT (H) PCB THICKNESS (T)	H+T = 3.4mm IC HEIGHT (H) PCB THICKNESS (T)	H+T = 3.9mm IC HEIGHT (H) PCB THICKNESS (T)	H+T = 4.4mm IC HEIGHT (H) PCB THICKNESS (T)
APPLIED FORCE (10 lbs)	4.5 lbs	4.8 lbs	5 lbs	5.3 lbs

PROJECT	APPROVED: CHRIS	MATERIAL: N/A	DATE: 2023/05/12	.X° ± 3°	
TITLE: HEAT SINK ASSEMBLY 50 x 50 x (6~40)mm	CHECKED: LEVI	FINISH: N/A	SCALE: 1 : 1	.X ± 0.30 .XX ± 0.20 .XXX ± 0.10	
PART NO: FN50004-xx35BA+PCM	DRAWN: VIC	UNITS: mm	REV: A	SHEET: 1 OF 1	



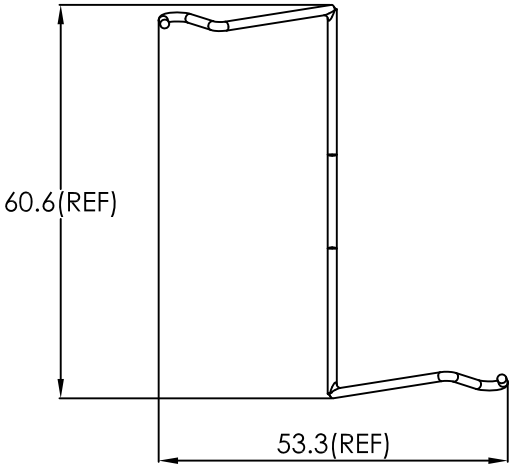


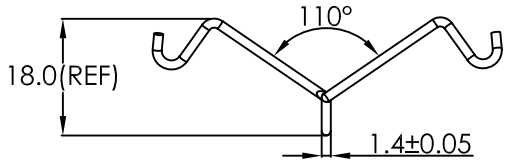


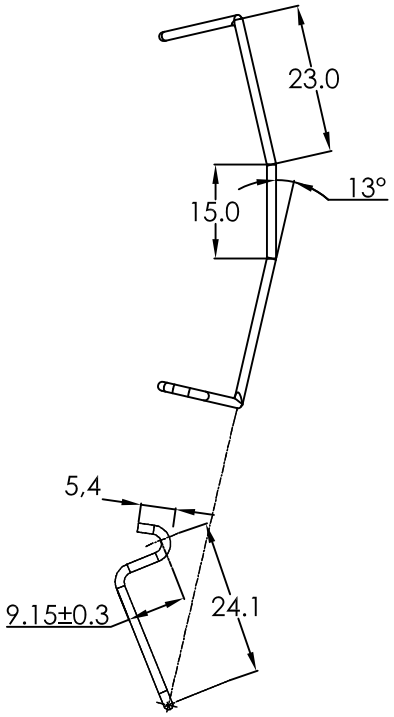
NOTES:

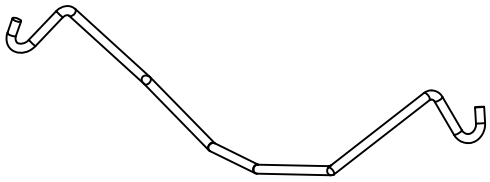
PART NAME / NUMBER	HEIGHT(H)
FN50004-0635BA-N	6
FN50004-0835BA-N	8
FN50004-1035BA-N	10
FN50004-1535BA-N	15
FN50004-2035BA-N	20
FN50004-2535BA-N	25
FN50004-3035BA-N	30
FN50004-3535BA-N	35
FN50004-4035BA-N	40

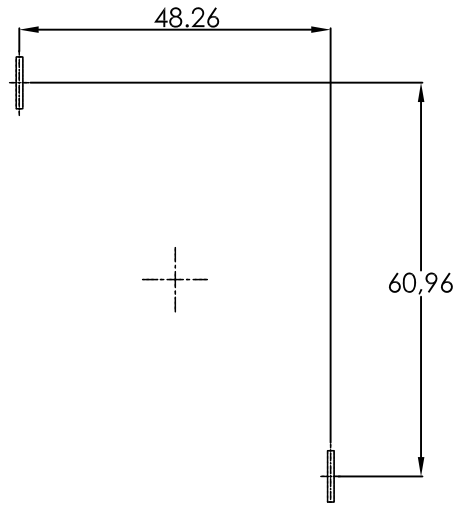
PROJECT	APPROVED: CHRIS	MATERIAL: AL1070	DATE: 2023/05/12	.X° ± 3°
TITLE: FORGED FIN 50 x 50 x (6~40)mm	CHECKED: LEVI	FINISH: BLACK MATTE ANODIZED	SCALE: 1 : 1	.X ± 0.30 .XX ± 0.20 .XXX ± 0.10
PART NO: FN50004-xx35BA-N	DRAWN: VIC	UNITS: mm	REV: A	SHEET: 1 OF 1







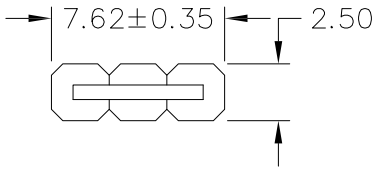


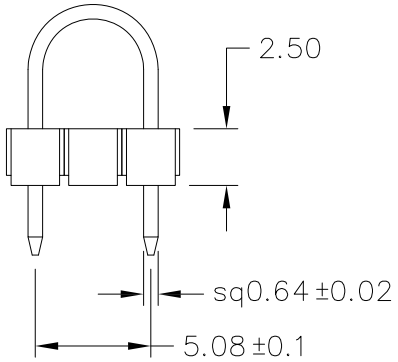


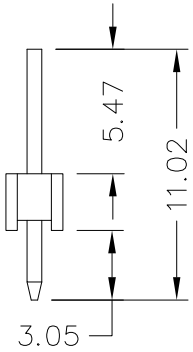
REF : ANCHOR LAYOUT

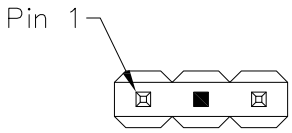
REGO

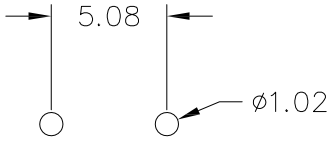
PROJECT	APPROVED: CHRIS	MATERIAL: PIANO WIRE	DATE: 2021/06/29	.X° ± 3°	
TITLE: WIRE CLIP	CHECKED: LEVI	FINISH: NICKEL	SCALE: 1 : 1	.X ± 0.30	.XX ± 0.20
PART NO: BCL6053-18	DRAWN: VIC	UNITS: mm	REV: A	.XXX ± 0.10	SHEET: 1 OF 1











Recommended P.C.B Layout

MATERIAL

Insulator : NYLON 6T or 9T
Contact Pin : Brass

SPECIFICATION

Current Rate : 3 AMP
Insulation Resistance : 5000MΩMin. at DC 500V
Contact Resistance : 20mΩMax. at DC 100mA
Dielectric Voltage : AC 500V for one minute
Operation Temperature : −40°C to + 105°C

81921U−9 1− 03 T B 01
(1 2 3 4 5 6)

1. 5: Normal Parts
   7: Green Product
   9: Green Product High Temp (NYLON 6T or 9T)
2. 1: Single row
3. No. of contacts per row
4. G: Gold flash
   S: Selective
   T: Tin plated
5. B: Black Insulator
6. REGO internal code.

.X ± 0.30	APPROVED: Chris	REGO® http://www.rego.com.tw	
.XX ± 0.20	CHECKED: Denny		
.XXX± 0.15	DRAWN: Bryan	TITLE: ANCHOR	
X° ± 3°	UNITS: mm	SCALE: NONE	PART NO:81921U−91−03TB01
			SHEET: 1 OF 1

REV	DATE
A	11.18.2015

PCM4988

High Thermal Conductivity Phase Change Material

Honeywell's PCM4988, a highly thermally conductive Phase Change Material (PCM) in pad format, was designed to minimize thermal resistance at interfaces. Based on a novel polymer PCM system, this material exhibits excellent wetting at interfaces during typical operating temperature range, resulting in very low surface contact resistance.

A proprietary filler material provides high thermal conductivity (2.0–5.0 W/m°C) and a low thermal impedance (<0.20°C cm^2/W), suitable for high performance IC devices.

PCM4988 in Convenient Pad Format

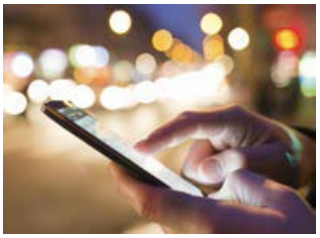
*Stencil printable material is available as PCM4988-SP

Honeywell TIMs Serve Multiple Applications

Automotive & Power

IT/Enterprise

Telecommunications



Consumer Electronics

FEATURES & BENEFITS

- High performance filler and polymer technology
- Phase change at 45°C
- Highly conductive filler loading to optimize performance
- Superior handling and reworkability
- Superior reliable thermal performance
- Excellent thermal capability to fit different needs

PCM4988 Technical Information

Physical Properties	Unit	Test Method	PCM4988
Thermal Conductivity	W/m·K	ASTM D5470	2.0
Thermal Impedance @ no shim (Typical Value)	°C -cm^2/W	ASTM D5470 Modified	0.14
Specific Gravity		ASTM D374	2.2
Viscosity (Typical Value)	Pa·s @2 1/s, 25°C	RehometerHON	NA
Volume Resistivity	Ω·cm	ASTM D257-700	8.2x10^{14}
Thickness Range	mm		0.20-1.00

STORAGE CONDITION

Refer to product label.

THERMAL IMPEDANCE POST RELIABILITY

(No shim @ 40psi)

End of Line 0.14 °C-cm^2/W

Temperature Cycle "B" 0.10 °C-cm^2/W

(-55°C to +125°C , 1000 cycles)

Product Use

Clamping pressure and temperature are suggested to achieve a minimum bond line thickness of the thermal interface material, typically less than 1.5 mil (0.038mm) for best thermal performance.

More Honeywell TIMs

PCM4988 is part of Honeywell's TIM Solutions family of phase change materials. Whatever the thermal challenge, we offer a TIM product that provides just the right characteristics for your application. Find out more about:

PTM7000 Series
PTM6000 Series
PTM5000 Series
PCM45F Series
Hybrid Series
LTM Series By

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